

February 1984 Revised May 2005

# MM74HCT273 Octal D-Type Flip-Flop with Clear

## **General Description**

The MM74HCT273 utilizes advanced silicon-gate CMOS technology. It has an input threshold and output drive similar to LS-TTL with the low standby power of CMOS.

These positive edge-triggered flip-flops have a common clock and clear-independent Q outputs. Data on a D input, having the specified set-up and hold time, is transferred to the corresponding Q output on the positive-going transition of the clock pulse. The asynchronous clear forces all outputs LOW when it is LOW.

All inputs to this device are protected from damage due to electrostatic discharge by diodes to  $V_{CC}$  and ground.

MM74HCT devices are intended to interface TTL and NMOS components to CMOS components. These parts can be used as plug-in replacements to reduce system power consumption in existing designs.

#### **Features**

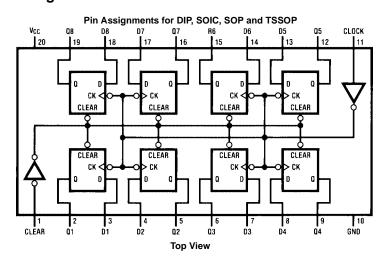
- Typical propagation delay: 20 ns
- Low quiescent current: 80 µA maximum (74HCT series)
- Fanout of 10 LS-TTL loads

## **Ordering Code:**

Order Number	Package Number	Package Description
MM74HCT273WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HCT273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HCT273MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HCT273N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Connection Diagram**



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DS005760

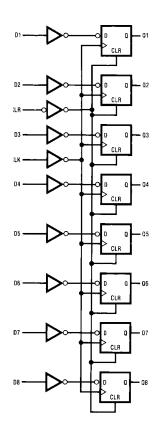
## **Truth Table**

(Each Flip-Flop)

	Outputs			
Clear	Clear Clock D			
L	Х	Х	L	
Н	<b>↑</b>	Н	Н	
Н	<b>↑</b>	L	L	
Н	L	Х	Q0	

- H = HIGH Level (steady-state)
  L = LOW Level (steady-state)
  X = Don't Care
  7 = Transition from LOW-to-HIGH level
  Q0 = The level of Q before the indicated steady-state input conditions were established.

## **Logic Diagram**



## **Absolute Maximum Ratings**(Note 1)

(Note 2)

 $\begin{array}{ll} \mbox{Power Dissipation ($P_D$)} \\ \mbox{(Note 3)} & 600 \ \mbox{mW} \\ \mbox{S.O. Package only} & 500 \ \mbox{mW} \end{array}$ 

Lead Temperature (T<sub>L</sub>)

(Soldering, 10 seconds) 260°C

## Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	4.5	5.5	V
DC Input or Output Voltage			
$(V_{IN}, V_{OUT})$	0	$V_{CC}$	V
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f)$		500	ns
Note 1: Absolute Maximum Patings are those	values b	ovond whi	oh dom

600 mW age to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power dissipation temperature derating—plastic "N" package: -12

mW/°C from 65°C to 85°C.

#### **DC Electrical Characteristics**

 $V_{\mbox{\footnotesize CC}} = 5V \pm 10\%$  unless otherwise specified

Symbol	Parameter	Conditions	$T_A = 25$ °C		$T_A = -40^{\circ}C$ to $85^{\circ}C$	T <sub>A</sub> = -55°C to 125°C	Units
			Тур		Guaranteed Limits		
V <sub>IH</sub>	Minimum HIGH Level			2.0	2.0	2.0	V
	Input Voltage						
V <sub>IL</sub>	Maximum LOW Level			0.8	0.8	0.8	V
	Input Voltage						
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IH}$ or $V_{IL}$					
	Output Voltage	$ I_{OUT}  = 20 \ \mu A$	$V_{CC}$	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	V
		$ I_{OUT} $ = 4.0 mA, $V_{CC}$ = 4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT} $ = 4.8 mA, $V_{CC}$ = 5.5V	5.2	4.98	4.84	4.7	V
V <sub>OL</sub>	Minimum LOW Level	$V_{IN} = V_{IH}$ or $V_{IL}$					
	Voltage	$ I_{OUT}  = 20 \mu A$	0	0.1	0.1	0.1	V
		$ I_{OUT} $ = 4.0 mA, $V_{CC}$ = 4.5V	0.2	0.26	0.33	0.4	V
		$ I_{OUT} $ = 4.8 mA, $V_{CC}$ = 5.5V	0.2	0.26	0.33	0.4	V
I <sub>IN</sub>	Maximum Input	$V_{IN} = V_{CC}$ or GND,		±0.1	±1.0	±1.0	μА
	Current	V <sub>IH</sub> or V <sub>IL</sub>					
I <sub>CC</sub>	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND		8	80	160	μА
	Supply Current	$I_{OUT} = 0 \mu A$					
		V <sub>IN</sub> = 2.4V or 0.5V (Note 4)		0.6	0.8	0.9	mA

Note 4: Measured per pin, all other inputs held at  $\rm V_{\rm CC}$  or GND.

## AC Electrical Characteristics $V_{CC} = 5V, T_A = 25^{\circ}C, C_L = 15 \ pF, t_r = t_f = 6 \ ns$

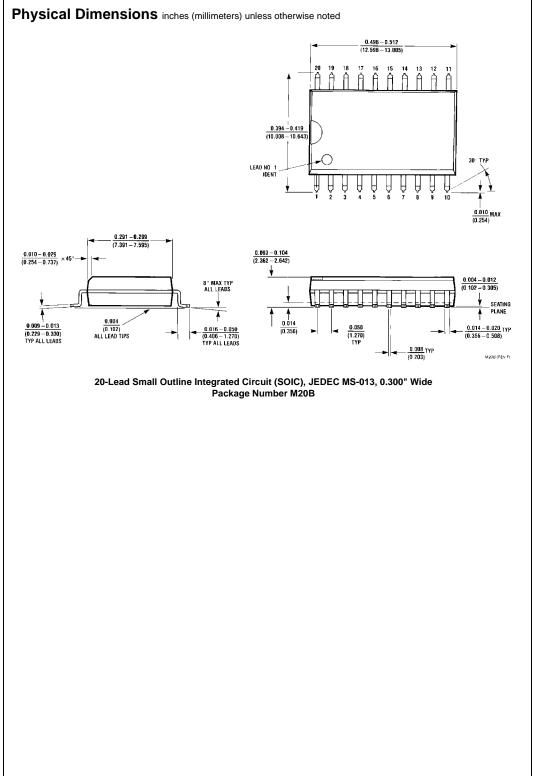
Symbol Parameter		Conditions	Тур	Guaranteed Limits	Units
f <sub>MAX</sub>	Maximum Operating Frequency		68	30	MHz
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay from Clock to Q		18	30	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay from Clear to Q		21	30	ns
t <sub>REM</sub>	Minimum Removal Time, Clear to Clock		-1	5	ns
t <sub>S</sub>	Minimum Set-Up Time D to Clock		6	20	ns
t <sub>H</sub>	Minimum Hold Time Clock to D		-3	5	ns
t <sub>W</sub>	Minimum Pulse Width Clock or Clear		10	16	ns

### **AC Electrical Characteristics**

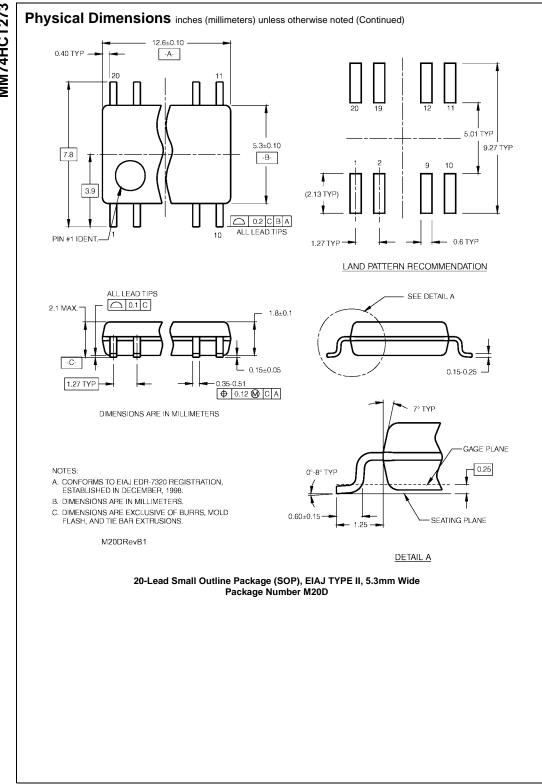
 $V_{CC} = 5.0V \pm 10\%$ ,  $C_L = 50$  pF,  $t_r = t_f = 6$  ns unless otherwise specified

Symbol	Parameter	Conditions	T <sub>A</sub> =	25°C	T <sub>A</sub> = -40°C to 85°C	T <sub>A</sub> = -55°C to 125°C	Units
			Тур		Guaranteed Limits		
$f_{MAX}$	Maximum Operating		68	27	21	18	MHz
	Frequency						
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		22	37	46	56	ns
	Delay from Clock to Q						
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		25	35	44	52	ns
	Delay from Clear to Q						
t <sub>REM</sub>	Minimum Removal		-1	5	6	7	ns
	Time Clear to Clock						
t <sub>S</sub>	Minimum Set-Up Time		6	20	25	30	ns
	D to Clock						
t <sub>H</sub>	Minimum Hold Time		-3	5	5	5	ns
	Clock to D						
t <sub>W</sub>	Minimum Pulse Width		10	16	25	30	ns
	Clock or Clear						
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise			500	500	500	ns
	and Fall Time, Clock						
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise		11	15	19	22	ns
	and Fall Time						
C <sub>PD</sub>	Power Dissipation	(Per Flip-Flop)	50				pF
	Capacitance (Note 5)						
C <sub>IN</sub>	Maximum Input		6	10	10	10	pF
	Capacitance						

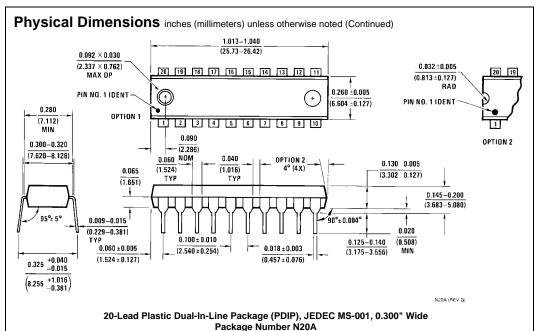
Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \, V_{CC}^2 \, f + I_{CC} \, V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \; V_{CC}^{\phantom{CC}2} \; f + I_{CC}. \label{eq:isomorphism}$ 



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## Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -0.20 64 4.4±0.1 -B-0.65 PIN #1 IDENT. LAND PATTERN RECOMMENDATION O.1 C ALL LEAD TIPS SEE DETAIL A -0.90<sup>+0.15</sup> 0.09-0.20 0.65 0.19-0.30 | \$\dag{0.10\dag{A} R\$ 0\$ R0.09mir GAGE PLANE DIMENSIONS ARE IN MILLIMETERS NOTES: A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93. 0.6±0.1 R0.09min -1.00 B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND THE BAR EXTRUSIONS. DETAIL A D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. MTC20REVD1 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20



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